

IGBT Modules

Power Module (X series) 1200V / 200A / 2-in-1 package

■ Features

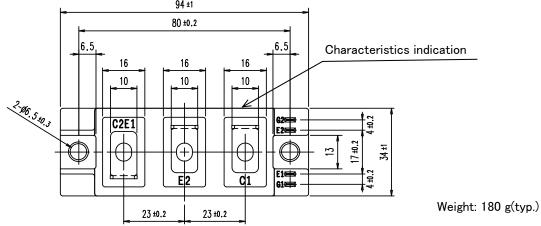
Low $V_{\rm CE(sat)}$ High speed switching Low Inductance Module structure

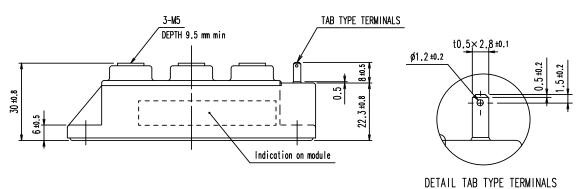
■ Applications

Inverter for Motor Drives, AC and DC Servo Drives Uniterruptible Power Supply Systems, Industrial machines, such as Welding machines

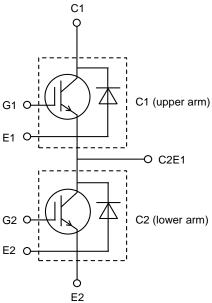


■ Outline drawing (Unit:mm)





■ Equivalent Circuit



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■ Absolute Maximum Ratings (at T_C= 25°C unless otherwise specified)

		Items	Symbols	Conc	litions	Maximum Ratings	Units	
	Collecto	r-emitter voltage,gate-emitter short-	V _{CES}			1200	V	
	Gate-emitter voltage,collector-emitter short-circuited		V_{GES}			±20	V	
<u>_</u>	Collecto	r current	I _C	Continuous	T _C =100°C	200		
Inverter	Repetitive peak collector current		I _{CRM}	1ms		400	A	
므	Forward current		I _F			200] A	
	Repetitive peak forward current		I _{FRM}	1ms		400		
	Total power dissipation		P _{tot}	1 device		830	W	
	Virtual junction temperature		T _{vj}			175		
	Operating virtual junction temperature		$T_{\rm vjop}$			175	°C	
Ca	Case temperature		Tc			125		
Storage temperature		${\cal T}_{ m stg}$			-40 ~ 125			
Isolation voltage between terminals and copper base (*1)		V_{isol}	AC: 1min.		4000	Vrms		
Mounting torque of screws to heatsink(*2)		Ms	M5		5.0	None		
Mounting torque of screws to terminals(*3)		$M_{\rm t}$	M5		5.0	N⋅m		

^(*1) All terminals should be connected together during the test.

^(*2) Recommendable Value: 3.0 ~ 5.0 N⋅m (M5 or M6)

^(*3) Recommendable Value: 2.5 ~ 5.0 N·m (M5)



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■ Electrical characteristics (at T_{vj}= 25°C unless otherwise specified)

	Itama	Conditions		no.	Characteristics			Units
	Items	Symbols	Conditions		min.	typ.	max.	Units
	Collector-emitter cut-off current,gate-emitter short-circuited	I _{CES}	$V_{\text{GE}} = 0V$ $V_{\text{CE}} = 1200V$		-	-	50	μA
	Gate leakage current,collector-emitter short-circuited	I _{GES}	V_{CE} =0V, V_{GE} =±20V		-	-	100	nA
	Gate-emitter threshold voltage	$V_{\rm GE(th)}$	$V_{\text{CE}} = 20V$ $I_{\text{C}} = 200\text{mA}$		6.0	6.5	7.0	V
		V _{CE(sat)} (terminal)		T _{vj} =25°C	-	1.70	2.15	
	Collector-emitter		V _{GE} = 15V	T _{vj} =25°C	-	1.45	1.90	1 .,
	saturation voltage	$V_{CE(sat)}$	I _C = 200A	T _{vi} =125°C	-	1.85	-	V
	_	(chip)		T _{vi} =150°C	-	1.90	-	
		(1 /		T _{vi} =175°C	-	1.95	-	+
	Internal gate resistance	$r_{\rm g}$	-	vj	-	5.00	-	Ω
	Input capacitance	C _{ies}			-	21	-	nF
	Output capacitance	Coes	$V_{CE}=10V, V_{GE}=0V, f=$	=1MHz	-	0.7	-	
	Reverse transfer capacitance	C _{res}	_ GL - , GL - ,		-	0.19	-	
	Gate charge	Q _G	$V_{\rm CC} = 600 \text{V}, I_{\rm C} = 200 \text{A}$ $V_{\rm GE} = -15 \rightarrow +15 \text{V}$		-	1.4	-	μC
Inverter		V _F (terminal)	$V_{GE} = 0V$ $I_F = 200A$	T _{vj} =25°C	-	1.85	2.30	
2				T _{vj} =25°C	-	1.60	2.05	Ī ,,
	Forward voltage	V_{F}		T _{vi} =125°C	-	1.65	-	V
		(chip)		T _{vi} =150°C	-	1.60	-	
				T _{vi} =175°C	-	1.60	-	
			$V_{CC} = 600V$ $I_{C}, I_{F} = 200A$ $V_{GE} = +15/-15V$ $R_{G} = 2.7 \Omega$	T _{vi} =25°C	-	0.39	-	
		$t_{\sf d(on)}$		T _{vj} =125°C	-	0.43	-	
	Turn-on delay time(*1)			T _{vj} =150°C	-	0.44	-	
				T _{vj} =175°C	-	0.45	-	
			$L_{\rm S} = 30 \rm nH$	$T_{\rm vj}$ =25°C		0.07		
	Rise time(*1)	$t_{ m r}$		T _{vj} =125°C	-	0.08	-	
	719E IIIIE(1)	ιŗ	T	T _{vj} =150°C	-	0.08	-	
				T _{vj} =175°C	-	0.09	-	
				$T_{\rm vj}$ =25°C	-	0.38	-	_
	Turn-off delay time(*1)	$t_{\sf d(off)}$		T _{vj} =125°C	-	0.42	-	μs
		- u(OII)		$T_{\rm vj}$ =150°C	-	0.43	-	_
			_	T_{vj} =175°C T_{vi} =25°C	-	0.44 0.10	-	_
	Fall time(*1)	t_{f}		$T_{vj} = 25^{\circ} \text{C}$	-	0.10	-	-
				$T_{vi} = 150^{\circ} C$	-	0.14	-	
				T _{vi} =175°C	-	0.14	-	
				$T_{\rm vi}$ =25°C	-	0.17	-	
	Reverse recovery time	t _{rr}		$T_{\rm vj} = 125^{\circ}{\rm C}$	-	0.30	-	4
				T_{vj} =150°C T_{vi} =175°C	-	0.32 0.36	-	-
				/ _{vj} =	•	0.30	<u> </u>	

^(*1) Turn-on time $(t_{on}) = t_{d(on)} + t_{r}$, Turn-off time $(t_{off}) = t_{d(off)} + t_{f}$



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■ Electrical characteristics (at T_{vj}= 25°C unless otherwise specified)

	Items	Symbols	Conditions		Characteristics			Units
	Items	Symbols			min.	typ.	max.	Ullits
			$V_{\rm CC} = 600 \rm V$	T _{vj} =25°C	-	15.1	-	
	Turn-on energy	E _{on}	$I_{\rm C}$, $I_{\rm F} = 200$ A	T _{vj} =125°C	-	24.5	-	
			$V_{GE} = +15/-15V$	T _{vj} =150°C	-	26.9	-	
			$R_G = 2.7 \Omega$	T _{vj} =175°C	-	29.2	-	
	Turn-off energy	E _{off}	$L_{\rm S} = 30 \rm nH$	T _{vj} =25°C	-	16.6	-	
ē				T _{vj} =125°C	-	20.0	-	
Inverter				T _{vj} =150°C	-	20.9	-	mJ
드				T _{vj} =175°C	-	21.7	-	
				T _{vj} =25°C	-	7.2	-	
	Reverse recovery energy	En		T _{vj} =125°C	-	13.1	-	
				T _{vj} =150°C	-	14.6	-]
				T _{vj} =175°C	-	16.0	-	1

NOTICE:

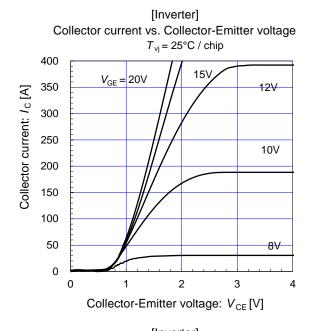
The external gate resistance ($R_{\rm G}$) shown above is one of our recommended value for the purpose of minimum switching loss. However the optimum $R_{\rm G}$ depends on circuit configuration and/or environment. We recommend that the $R_{\rm G}$ has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

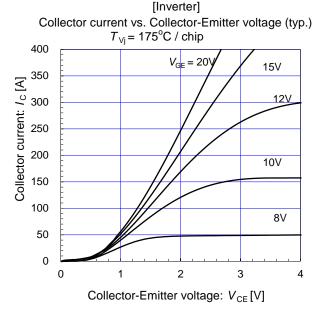
■Thermal resistance characteristics

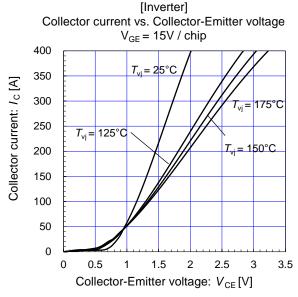
	Symbols	Conditions	Characteristics			no
	Symbols	Conditions	min.	typ.	max.	ns
Thermal resistance junction to case	$R_{ m th(j-c)}$	IGBT	-	-	0.180	K/W
(1device)	th(J-c)	FWD	-	-	0.271	
Thermal resistance case to heatsink (1IGBT + 1FWD) (*1)	R _{th(c-s)}	with 1 W/(m·K) thermal grease	-	0.050	-	10,00

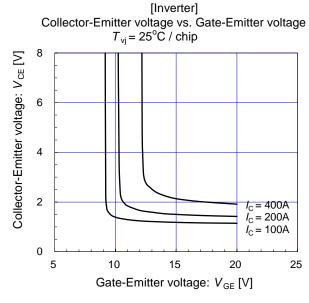
^(*1) This is the value which is defined mounting on the additional heatsink with thermal grease.

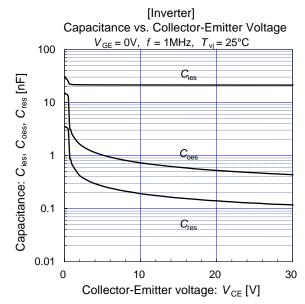


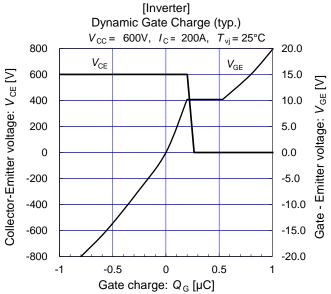


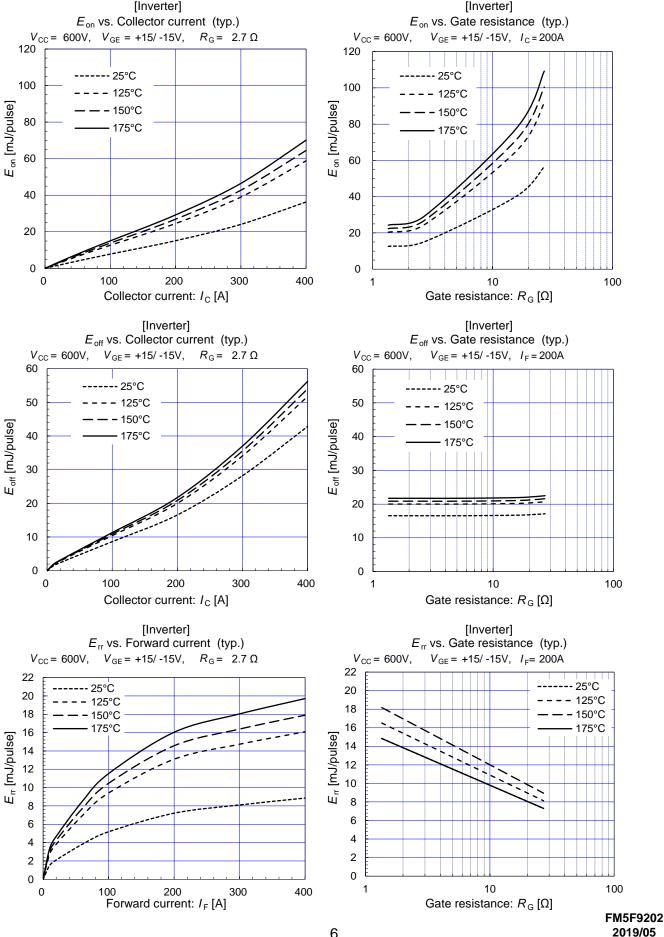




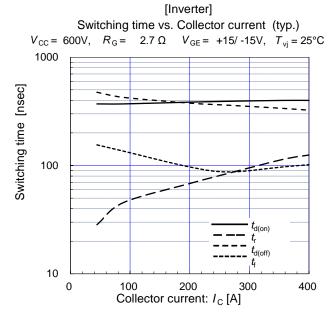


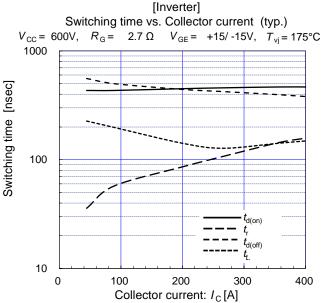


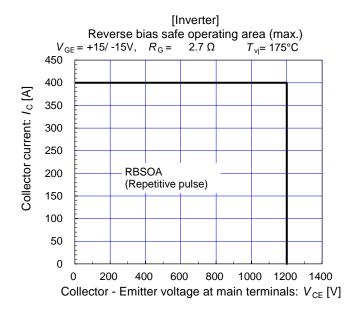


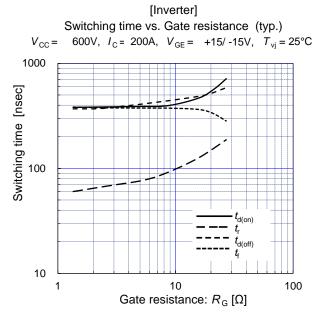


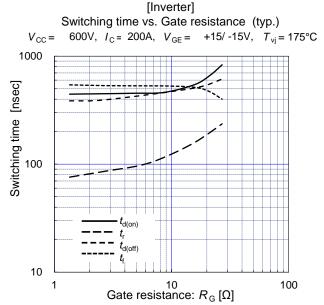




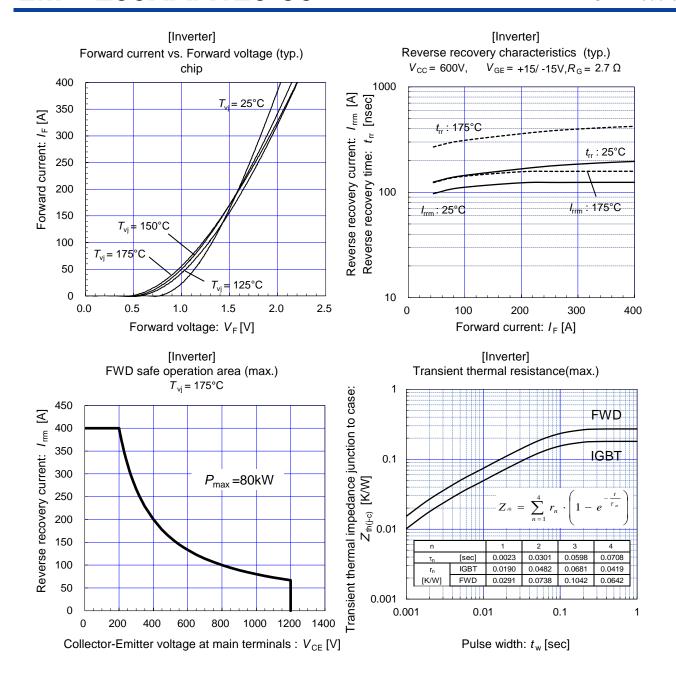












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